



Material Content Data Sheet



Sales Product Name		BSC084P03NS3E G		Issued		19. July 2018		
MA#		MA001408428						
Package		PG-TDSON-8-5		Weight*		124.36 mg		
Construction Element	Material Group	Substances	CAS# if applicable	Weight [mg]	Average Mass [%]	Sum [%]	Average Mass [ppm]	Sum [ppm]
chip	inorganic material	silicon	7440-21-3	1.835	1.48	1.48	14754	14754
leadframe	non noble metal	iron	7439-89-6	0.038	0.03		304	
	inorganic material	phosphorus	7723-14-0	0.011	0.01		91	
	non noble metal	copper	7440-50-8	37.762	30.36	30.40	303646	304041
wire	non noble metal	copper	7440-50-8	0.057	0.05	0.05	459	459
encapsulation	organic material	carbon black	1333-86-4	0.095	0.08		764	
	plastics	epoxy resin	-	6.749	5.43		54268	
	inorganic material	silicondioxide	60676-86-0	40.683	32.71	38.22	327138	382170
leadfinish	non noble metal	tin	7440-31-5	1.470	1.18	1.18	11819	11819
plating	noble metal	silver	7440-22-4	0.166	0.13	0.13	1331	1331
solder	noble metal	silver	7440-22-4	0.046	0.04		370	
	non noble metal	tin	7440-31-5	0.037	0.03		296	
	non noble metal	lead	7439-92-1	1.758	1.41	1.48	14133	14799
heatspreader	non noble metal	iron	7439-89-6	0.011	0.01		91	
	inorganic material	phosphorus	7723-14-0	0.003	0.00		27	
	non noble metal	copper	7440-50-8	11.320	9.10	9.11	91026	91144
heat sink CLIP	inorganic material	phosphorus	7723-14-0	0.007	0.01		54	
	non noble metal	iron	7439-89-6	0.022	0.02		179	
	non noble metal	copper	7440-50-8	22.292	17.92	17.95	179250	179483
*deviation	< 10%		Sum in total:			100.00		1000000

Important Remarks:

1. Infineon Technologies AG provides full material declaration based on information provided by third parties and has taken and continues to take reasonable steps to provide representative and accurate information.
2. Infineon Technologies AG and Infineon Technologies AG suppliers consider certain information to be proprietary, and thus CAS numbers and other limited information may not be available for release.
3. All statements are based on our present knowledge, are provided 'as is' and may be subject to change at any time due to technical requirements and development without notification.

This product is in compliance with EU Directive 2015/863/EU amending Annex II to EU Directive 2011/65/EU (RoHS) and contains Pb according RoHS exemption 7a, Lead in high melting temperature type solders.

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